

20V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = 25°C		
-20V	600mΩ @ V _{GS} = -4.5V	-0.92A		
	900mΩ @ V _{GS} = -2.7V	-0.75A		

Description and Applications

This MOSFET utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed, making it ideal for high-efficiency power management applications.

- DC DC converters
- Power management functions
- Disconnect switches
- Motor control

Features and Benefits

- · Fast switching speed
- Low on-resistance
- Low threshold
- Low gate drive
- "Lead Free", RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

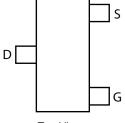
Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish; Solderable per MIL-STD-202, Method 208
- Weight: 0.008 grams (approximate)

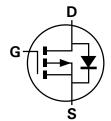
SOT23



Top View



Top View Pin Out



Equivalent Circuit

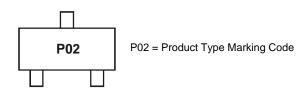
Ordering Information (Note 3)

-						
Product		Marking	Reel size (inches)	Tape width (mm)	Quantity per reel	
	ZXM61P02FTA	P02	7	8	3000 Units	

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.twtysemi.com
- 3. For packaging details, go to our website at http://www.twtysemi.com

Marking Information





Maximum Ratings $@T_A = 25^{\circ}C$ unless otherwise specified

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	-20	V
Gate-Source Voltage			V_{GS}	±12	V
Continuous Drain Current	V _{GS} = 4.5V	$T_A = 25^{\circ}C \text{ (Note 5)}$ $T_A = 70^{\circ}C \text{ (Note 5)}$	I _D	-0.9 -0.7	А
Pulsed Drain Current (Note 6)			I _{DM}	-4.9	A
Continuous Source Current (Body Diode) (Note 5)		I _S	-0.9	А	
Pulsed Source Current (Body Diode) (Note 6)			I _{SM}	-4.9	Α

Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 4)	В	625	mW
Linear Derating Factor	P _D	5	mW/°C
Power Dissipation (Note 5)	D-	806	mW
Linear Derating Factor	P _D	6.4	mW/°C
Thermal Resistance, Junction to Ambient (Note 4)	$R_{ heta JA}$	200	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	R ₀ JA	155	°C/W
Operating and Storage Temperature Range	$T_{J_i}T_{STG}$	-55 to +150	°C

Notes:

- 4. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions 5. For a device surface mounted on FR4 PCB measured at t ≤5 secs.
 6. Repetitive rating 25mm x 25mm FR4 PCB, D=0.05 pulse width=10µs pulse current limited by maximum junction temperature.



Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$I_D = -250 \mu A, V_{GS} = 0 V$
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-0.1	μΑ	$V_{DS} = -20V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	-0.7	_	_	V	$I_D = -250 \mu A$, $V_{DS} = V_{GS}$
Static Drain-Source On-Resistance (Note 7)	2	_		0.6	Ω	$V_{GS} = -4.5V, I_D = -0.61A$
Static Dialif-Source Off-Resistance (Note 1)	R _{DS} (ON)			0.9		$V_{GS} = -2.7V$, $I_D = -0.31A$
Forward Transconductance (Notes 7 and 9)	g fs	0.56	_	_	S	$V_{DS} = -10V, I_{D} = -0.31A$
Diode Forward Voltage (Note 7)	V_{SD}	_	_	-0.95	V	$T_J = 25$ °C, $I_S = -0.61$ A, $V_{GS} = 0$ V
Reverse Recovery Time (Note 9)	t _{rr}	_	14.9	_	ns	$T_J = 25^{\circ}C$, $I_F = -0.61A$,
Reverse Recovery Charge (Note 9)	Q_{rr}	_	5.6	_	nC	di/dt = 100A/μs
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss	_	150	_		$V_{DS} = -15V, V_{GS} = 0V$ f = 1.0MHz
Output Capacitance	Coss	_	70	_	pF	
Reverse Transfer Capacitance	Crss	_	30	_		
Turn-On Delay Time (Note 8)	t _{d(on)}	_	2.9	_		
Turn-On Rise Time (Note 8)	t _r	_	6.7	_		$\begin{split} V_{DD} &= \text{-}110\text{V}, \ I_D = \text{-}0.93\text{A}, \\ R_G &\cong 6.2\Omega, \ R_D \cong 11\Omega, \end{split}$
Turn-Off Delay Time (Note 8)	t _{d(off)}	_	11.2	_	ns	
Turn-Off Fall Time (Note 8)	t _f	_	10.1	_		
Total Gate Charge (Note 8)	Qg	_	3.5	_		$V_{DS} = -16V$, $V_{GS} = -4.5V$, $I_{D} = -0.61A$
Gate-Source Charge (Note 8)	Q_{gs}	_	0.5	_	nC	
Gate-Drain Charge (Note 8)	Q _{gd}	_	1.5	_		

Notes:

- 7. Measured under pulsed conditions. Pulse width = $300\mu s$. Duty cycle $\leq 2\%$.
- Switching characteristics are independent of operating junction temperature.
 For design aid only, not subject to production testing.